

MOSFETs Silicon N-Channel MOS

SSM6N7002CFU

1. Applications

· High-Speed Switching

2. Features

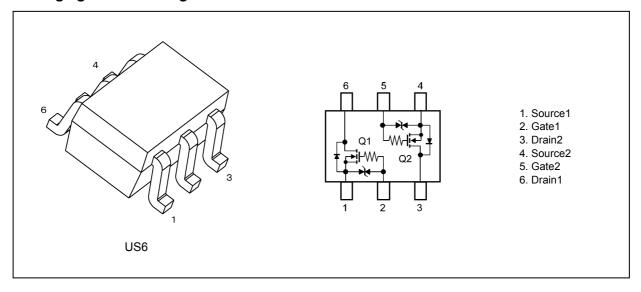
- (1) Gate-Source diode for protection
- (2) Low drain-source on-resistance

: $R_{DS(ON)}$ = 2.8 Ω (typ.) (@ V_{GS} = 10 V, I_D = 100 mA)

 $R_{\rm DS(ON)}$ = 3.1 Ω (typ.) (@V_{\rm GS} = 5 V, $I_{\rm D}$ = 100 mA)

 $R_{\rm DS(ON)} = 3.2~\Omega$ (typ.) (@ $V_{\rm GS} = 4.5~{\rm V},~I_{\rm D} = 100~{\rm mA}$)

3. Packaging and Pin Assignment





4. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C) (Q1,Q2 Common)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	60	V
Gate-source voltage		V_{GSS}	±20	
Drain current (DC)	(Note 1)	Ι _D	170	mA
Drain current (pulsed)	(Note 1), (Note 2)	I_{DP}	680	
Power dissipation	(Note 3)	P_D	285	mW
Channel temperature		T _{ch}	150	°C
Storage temperature		T _{stg}	-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- Note 1: Ensure that the channel temperature does not exceed 150 °C.
- Note 2: Pulse width (PW) \leq 10 μ s, duty \leq 1%
- Note 3: Device mounted on an FR-4 board.(total dissipation) (25.4 mm \times 25.4 mm \times 1.6 mm ,Cu pad: 645 mm²)

Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.

Note: The channel-to-ambient thermal resistance, R_{th(ch-a)}, and the drain power dissipation, P_D, vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.

5. Electrical Characteristics

5.1. Static Characteristics (Unless otherwise specified, T_a = 25 °C)(Q1,Q2 Common)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	V_{DS} = 0 V, V_{GS} = ±16 V	_	_	±2	μА
			$V_{DS} = 0 \text{ V}, V_{GS} = \pm 10 \text{ V}$	_	_	±0.5	
			$V_{DS} = 0 \text{ V}, V_{GS} = \pm 5 \text{ V}$	_	_	±0.1	
Drain cut-off current		I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V	_	_	1	μΑ
			$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V},$ $T_j = 150 \text{ °C}$	_	_	200	
Drain-source breakdown voltage		V _{(BR)DSS}	I _D = 250 μA, V _{GS} = 0 V	60	_	_	V
Gate threshold voltage	(Note 1)	V _{th}	$I_D = 250 \mu A, V_{DS} = V_{GS}$	1.1	_	2.1	V
Drain-source on-resistance	(Note 2)	R _{DS(ON)}	I _D = 100 mA, V _{GS} = 10 V	_	2.8	3.9	Ω
			I_D = 100 mA, V_{GS} = 10 V, T_j = 150 °C	_	5.4	8.1	
			I _D = 100 mA, V _{GS} = 5 V	_	3.1	4.4	
			I _D = 100 mA, V _{GS} = 4.5 V	_	3.2	4.7	
Forward transfer admittance	(Note 2)	Y _{fs}	V _{DS} = 10 V, I _D = 200 mA	_	450	_	mS

Note 1: Let V_{th} be the voltage applied between gate and source that causes the drain current (I_D) to below (250 μ A for this device). Then, for normal switching operation, $V_{GS(ON)}$ must be higher than V_{th} , and $V_{GS(OFF)}$ must be lower than V_{th} . This relationship can be expressed as: $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$.

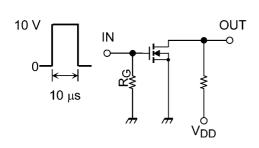
Take this into consideration when using the device.

Note 2: Pulse measurement.

5.2. Dynamic Characteristics (Unless otherwise specified, T_a = 25 °C)(Q1,Q2 Common)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$	_	11	17	pF
Reverse transfer capacitance	C _{rss}	f = 1 MHz	_	0.7	_	
Output capacitance	Coss		_	3	_	
Switching time (turn-on delay time)	t _{d(on)}	V _{DD} = 40 V, I _D = 160 mA,	_	2	4	ns
Switching time (rise time)	t _r	$V_{GS} = 0 \text{ to } 10 \text{ V}, R_{G} = 50 \Omega$	_	3	_	
Switching time (turn-off delay time)	t _{d(off)}		_	7	14	
Switching time (fall time)	t _f		_	24	_	

5.3. Switching Time Test Circuit





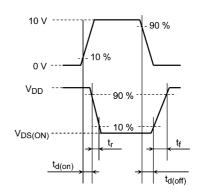


Fig. 5.3.2 Input Waveform/Output Waveform

5.4. Gate Charge Characteristics (Unless otherwise specified, T_a = 25 °C) (Q1,Q2 Common)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	V_{DS} = 30 V, I_{D} = 200 mA,	_	0.27	0.35	nC
Gate-source charge	Q _{gs}	V _{GS} = 4.5 V	_	80.0		
Gate-drain charge	Q _{gd}		_	0.08	_	

5.5. Source-Drain Characteristics (Unless otherwise specified, T_a = 25 °C) (Q1,Q2 Common)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Diode forward voltage (Note	e 1) V _{DSF}	I _D = -115 mA, V _{GS} = 0 V	_	-0.87	-1.2	V

Note 1: Pulse measurement.

6. Marking

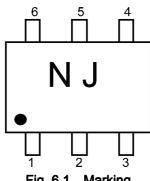


Fig. 6.1 Marking

7. Characteristics Curves (Q1,Q2 Common) (Note)

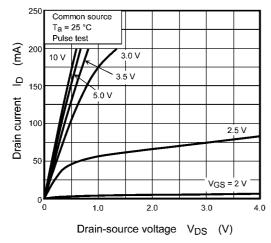


Fig. 7.1 I_D - V_{DS}

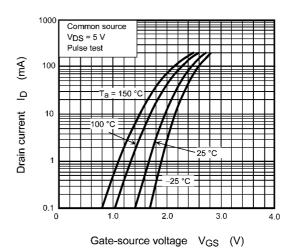


Fig. 7.2 I_D - V_{GS}

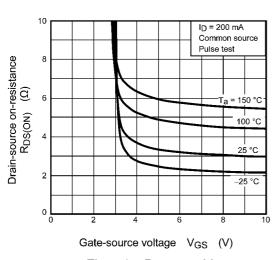


Fig. 7.3 R_{DS(ON)} - V_{GS}

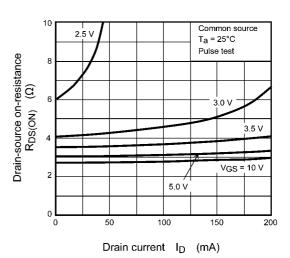


Fig. 7.4 R_{DS(ON)} - I_D

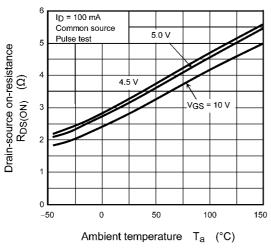


Fig. 7.5 R_{DS(ON)} - T_a

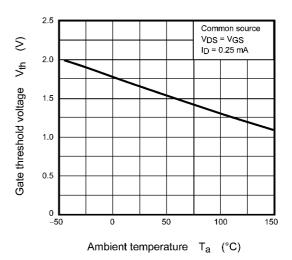
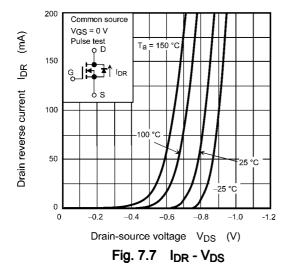


Fig. 7.6 V_{th} - T_a



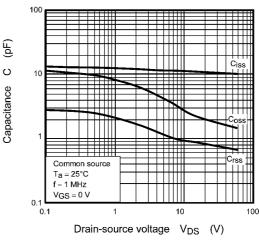
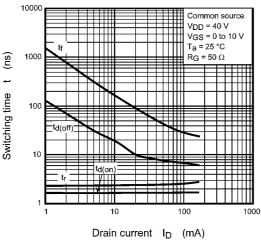


Fig. 7.8 C - V_{DS}



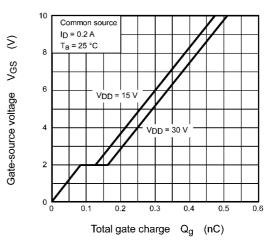
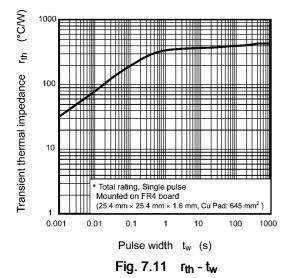


Fig. 7.9 t - I_D

Fig. 7.10 Dynamic Input Characteristics



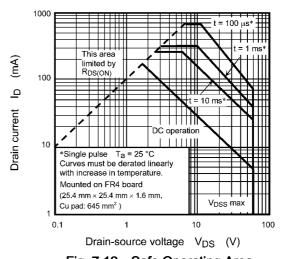


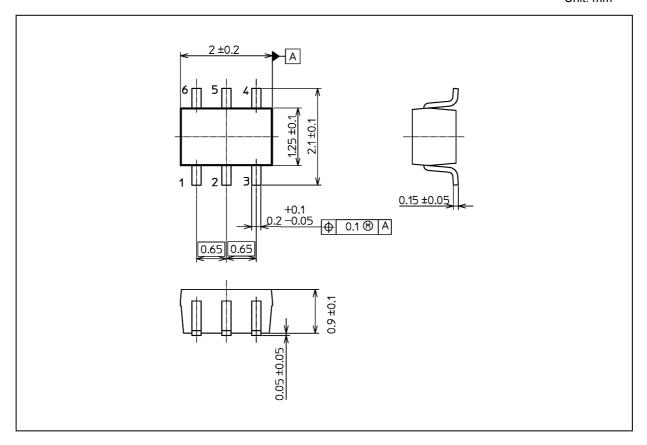
Fig. 7.12 Safe Operating Area

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



Package Dimensions

Unit: mm



Weight: 6.8 mg (typ.)

	Package Name(s)	
Nickname: US6		



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